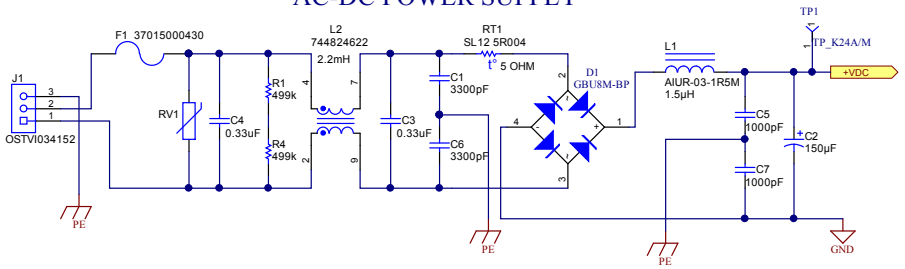
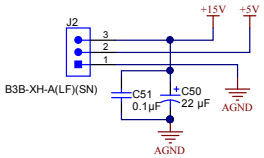
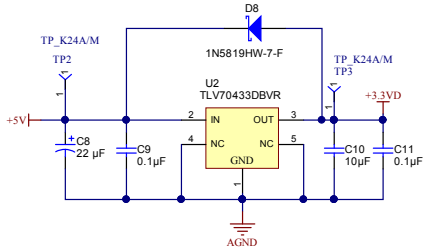
AC-DC POWER SUPPLY



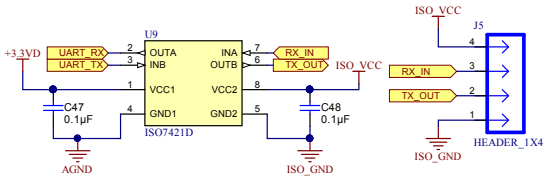
Auxiliary Power Supply Connector



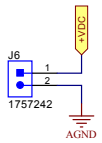
3.3V LDO for powering the MCU

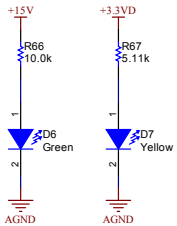


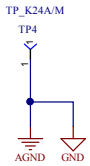
Isolated UART Interface



+VDC Connector for Powering the Auxiliary Power Supply Board







Number: TIDA-00472	Rev: E1	Designed for: Public Release	Mod. Date: 10/27/2015
SVN Rev: Version control disabled		Project Title: 230V, 250W, Mains Powered BLDC Motor Drive	
Drawn By:		Sheet Title:	
Engineer: Manu Balakrishnan		Assembly Variant: 001	Sheet: 1 of 4
		File: Pg1-Cover_1.SchDoc	Size: B
		Contact: http://www.ti.com/support	

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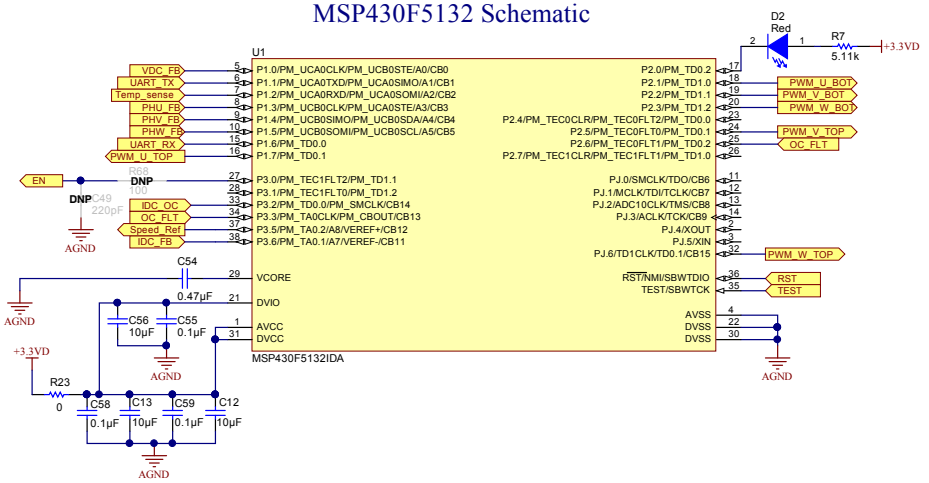
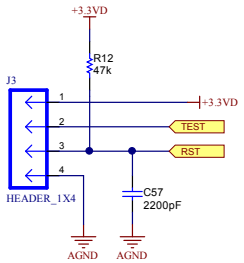
MSP430F5132 Schematic

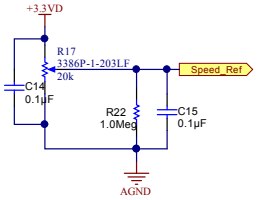


Programming Connector for MSP430

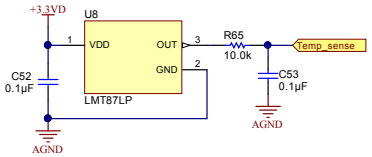


Power Supply Supervisor for MCU

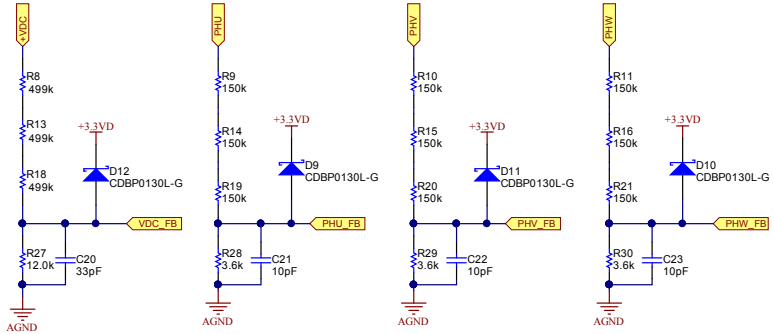
Speed Referebce through Potentiometer



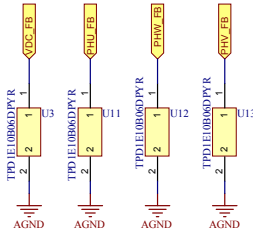
Temperature Sensor



DC Bus & Winding Voltage Sense Feedback

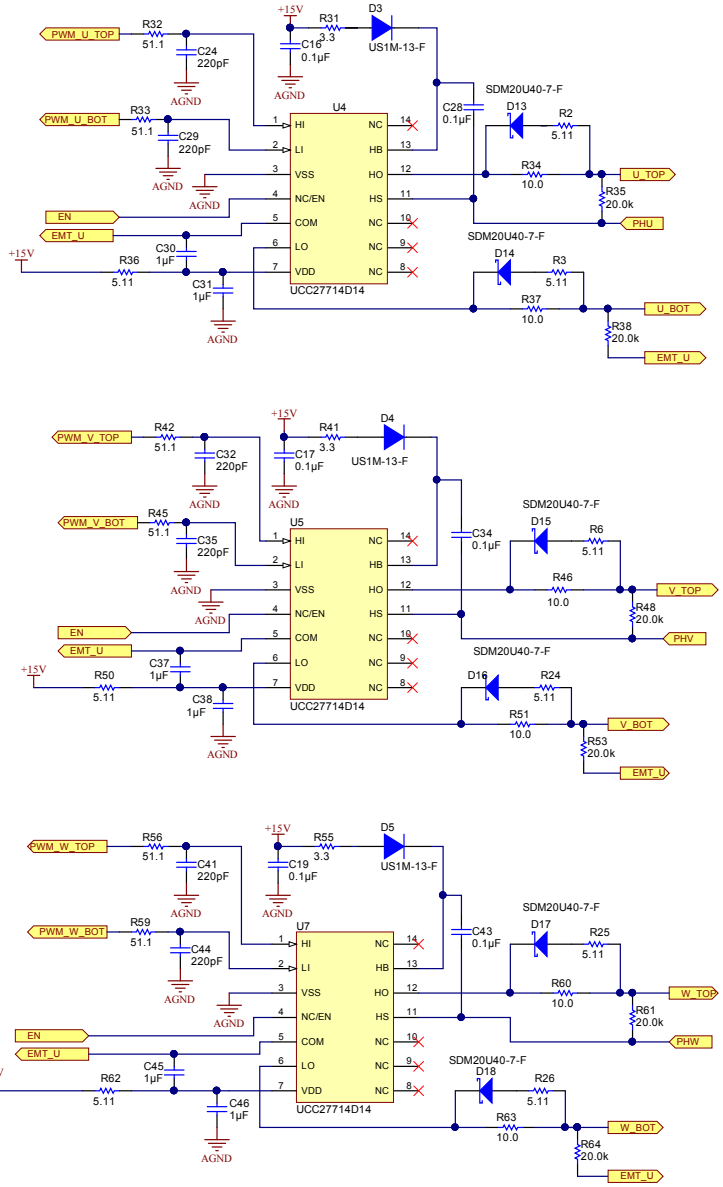


ESD Protection for Voltage Sensing

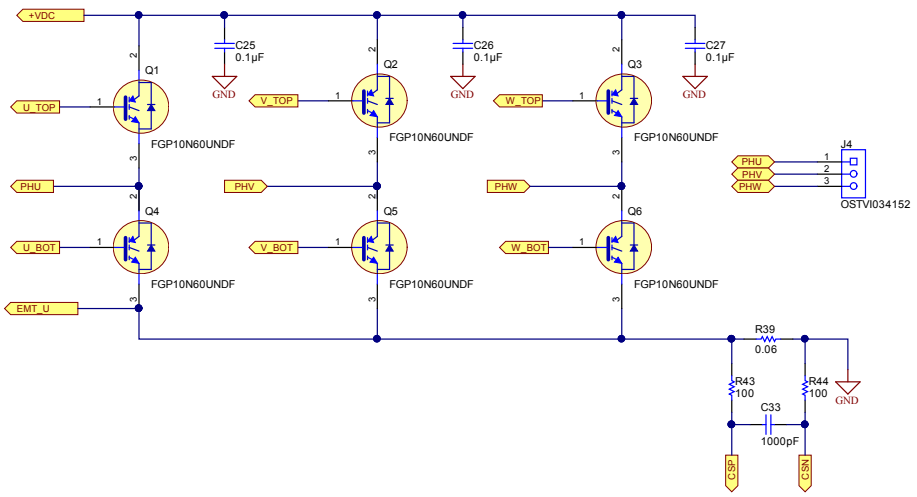


Number: TIDA-00472	Rev: E1	Designed for: Public Release	Mod. Date: 10/27/2015
Custom Rev: Version control disabled		Project Title: 230V, 250W, Mains Powered BLDC Motor Drive	
Drawn By: Manu Balakrishnan		Sheet Title: Main	
Engineer: Manu Balakrishnan		Assembly Variant: 001	Sheet: 2 of 4
		File: Pg2-Main_1.SchDoc	Size: B
		Contact: http://www.ti.com/support	http://www.ti.com

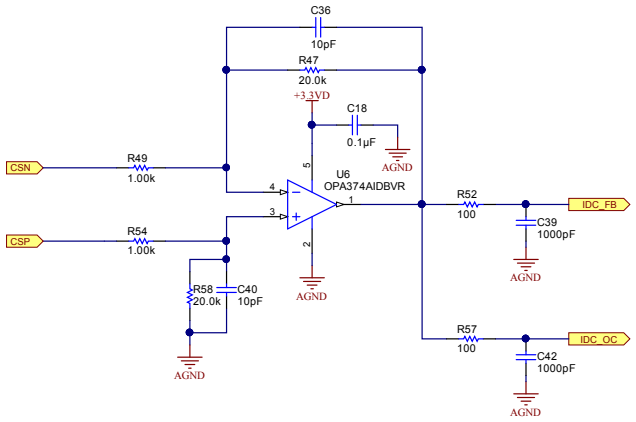
Gate Driver



Three Phase Inverter



Current Sense Amplifier



Number: TIDA-00472	Rev: E1	Designed for: Public Release	Mod. Date: 10/27/2015
SVN Rev: Version control disabled		Project Title: 230V, 250W, Mains Powered BLDC Motor Drive	
Drawn By: Manu Balakrishnan		Sheet Title: Main	
Engineer: Manu Balakrishnan		Assembly Variant: 001	Sheet: 3 of 4
		File: Pg3-Main.SchDoc	Size: B
		Contact: http://www.ti.com/support	http://www.ti.com

PCB Number: TIDA-00472
PCB Rev: E2

LBL1

H1 NY PMS 440 0025 PH

H2 NY PMS 440 0025 PH

H3 NY PMS 440 0025 PH

H4 NY PMS 440 0025 PH

PCB
LOGO
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Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Number: TIDA-00472	Rev: E1	Designed for: Public Release	Mod. Date: 9/23/2015
SVN Rev: Version control disabled		Project Title: 230V, 250W, Mains Powered BLDC Motor Drive	
Drawn By: Manu Balakrishnan		Sheet Title: Main	
Engineer: Manu Balakrishnan		Assembly Variant: 001	Sheet: 4 of 4
		File: Pg4-Hardware.SchDoc	Size: B
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